

LS3250SA NPN TRANSISTOR



Linear Systems NPN Transistor

The LS3250SA is a NPN transistor mounted in a single TO-92 package.

The 3 Pin TO-92 provides ease of manufacturing.

(See Packaging Information).

LS3250SA Features:

Low Output Capacitance

FEATURES			
LOW OUTPUT CAPACITANCE	≤ 2pF		
ABSOLUTE MAXIMUM RATINGS 1			
@ 25°C (unless otherwise noted)			
Maximum Temperatures			
Storage Temperature	-65°C to +150°C		
Operating Junction Temperature	-55°C to +150°C		
Maximum Power Dissipation			
Continuous Power Dissipation	TBD		
Maximum Currents			
Collector Current	50mA		
Maximum Voltages			
Collector to Collector Voltage	80V		

ELECTRICAL CHARACTERISTICS @ 25°C (unless otherwise noted)

		,				
SYMBOL	CHARACTERISTICS	MIN.	TYP.	MAX.	UNITS	CONDITIONS
BV_{CBO}	Collector to Base Voltage	45			V	I _C = 10mA, I _E = 0
BV_{CEO}	Collector to Emitter Voltage	45			V	$I_{C} = 10 \mu A, I_{B} = 0$
BV _{EBO} ²	Emitter-Base Breakdown Voltage	6.2			٧	$I_{E} = 10 \mu A, I_{C} = 0$
BV_{CCO}	Collector to Collector Voltage	80			٧	$I_{C} = 10 \mu A, I_{E} = 0$
		150				$I_C = 10 \mu A, V_{CE} = 5V$
h _{FE}	DC Current Gain	120				I _C = 100μA, V _{CE} = 5V
		100				$I_{C} = 1 \text{mA}, V_{CE} = 5 \text{V}$
V _{CE} (SAT)	Collector Saturation Voltage			0.25	V	$I_{C} = 100 \text{mA}, I_{B} = 10 \text{mA}$
I _{EBO}	Emitter Cutoff Current			0.2	nA	$I_C = 0A$, $V_{CB} = 3V$
I _{CBO}	Collector Cutoff Current			0.2	nA	$I_E = 0A, V_{CB} = 20V$
C _{OBO}	Output Capacitance			2	pF	$I_E = 0A, V_{CB} = 10V$
f_T	Current Gain Bandwidth Product	-	-	600	MHz	$I_C = 1 \text{mA}, V_{CE} = 5 \text{V}$
NF	Narrow Band Noise Figure			3	dB	$I_C = 100 \mu A$, $V_{CE} = 5V$, BW=200Hz, $R_B = 10 \Omega$,
						f = 1KHz

Notes:

- 1. Absolute Maximum ratings are limiting values above which serviceability may be impaired
- 2. The reverse base-to-emitter voltage must never exceed 6.2 volts; the reverse base-to-emitter current must never exceed $10\mu A$.



T0-92 (Bottom View)

Available Packages:

LS3250SA in TO-92 LS3250SA available as bare die

Please contact Micross for full package and die dimensions:

Email: chipcomponents@micross.com
Web: www.micross.com/distribution.aspx

